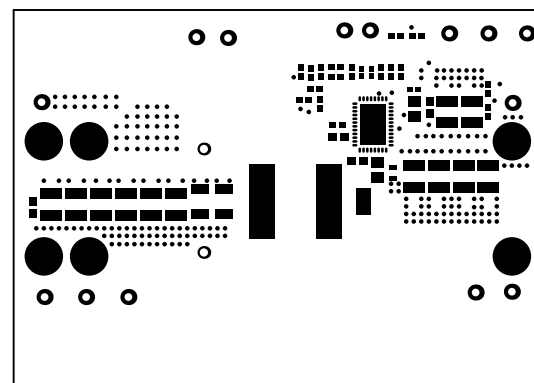
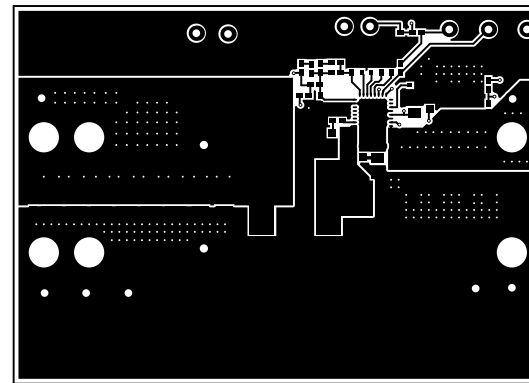


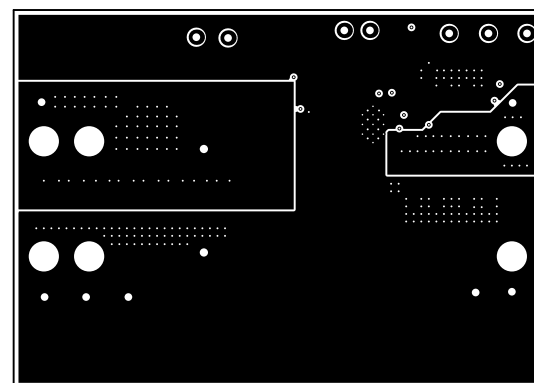
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20050	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: PMP20050		
PLOT NAME = Top Overlay	GENERATED : 4/13/2017 8:30:05 AM	TEXAS INSTRUMENTS	



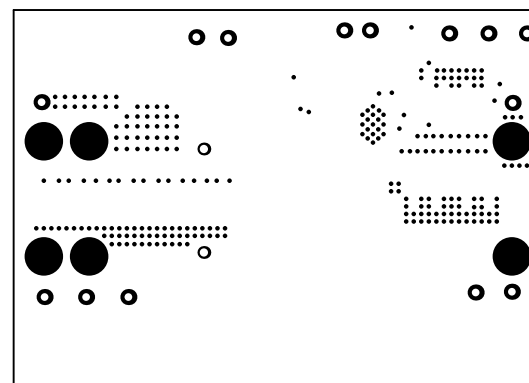
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20050	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: PMP20050		
PLOT NAME = Top Solder Mask	GENERATED : 4/13/2017 8:30:06 AM	TEXAS INSTRUMENTS	



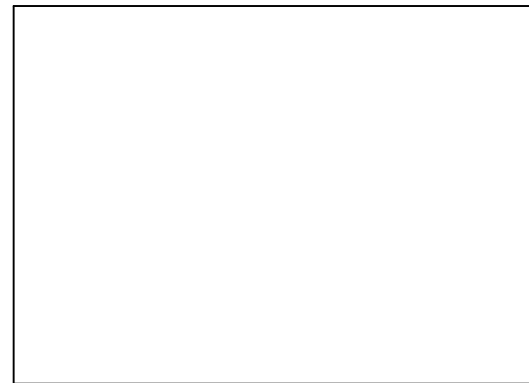
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20050	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: PMP20050		
PLOT NAME = Top Layer	GENERATED : 4/13/2017 8:30:07 AM	TEXAS INSTRUMENTS	



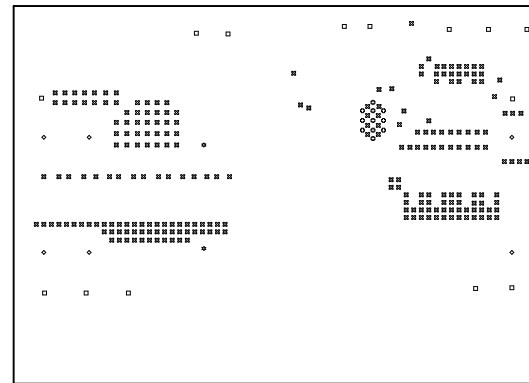
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20050	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: PMP20050		
PLOT NAME = Bottom Layer	GENERATED : 4/13/2017 8:30:08 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20050	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: PMP20050		
PLOT NAME = Bottom Solder Mask	GENERATED : 4/13/2017 8:30:09 AM	TEXAS INSTRUMENTS	

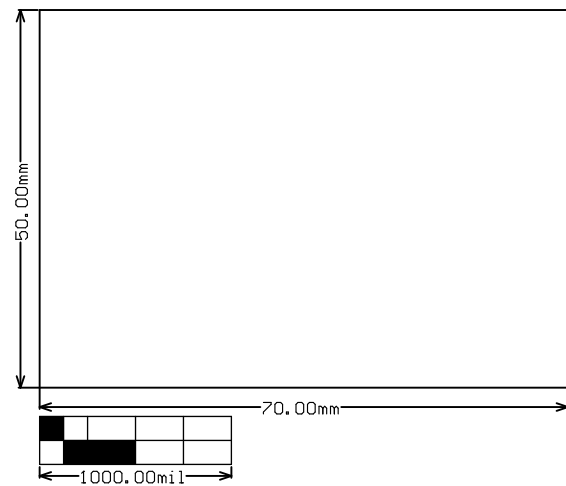


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20050	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: PMP20050		
PLOT NAME = Bottom Overlay	GENERATED : 4/13/2017 8:30:10 AM		TEXAS INSTRUMENTS



Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Tolerance
⊕	11	7.87mil (0.200mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	231	10.00mil (0.254mm)	PTH	Round	Top Layer - Bottom Layer	
□	14	40.00mil (1.016mm)	PTH	Round	Top Layer - Bottom Layer	
⊛	2	43.00mil (1.092mm)	PTH	Round	Top Layer - Bottom Layer	
◇	6	157.48mil (4.000mm)	PTH	Round	Top Layer - Bottom Layer	
	264 Total					

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20050	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: PMP20050		
PLOT NAME = Drill Drawing	GENERATED : 4/13/2017 8:30:11 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20050	REV: A	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: PMP20050		
PLOT NAME = Board Dimensions	GENERATED : 4/13/2017 8:30:12 AM	TEXAS INSTRUMENTS	

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